

1. Part No. Expression:

W 1 2 1 0 F 9 0 0 - R B - □□

(a) (b) (c) (d) (e)(f) (g)

a) Series Code

b) Dimension Code

c) Material Code

d) Impedance Code

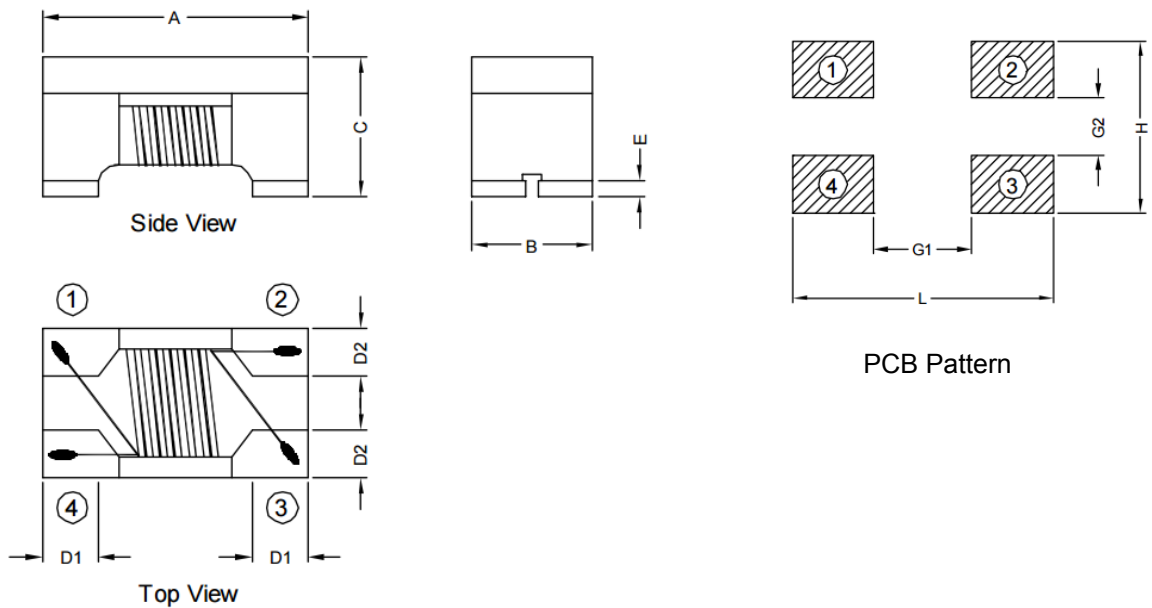
e) R: Tape & Reel

f) Rated Current B: 200mA

g) 10: Standard

11-99 : Internal Controlled Number

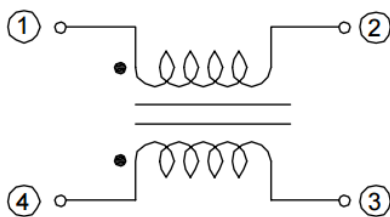
2. Configuration & Dimensions :



Unit: mm

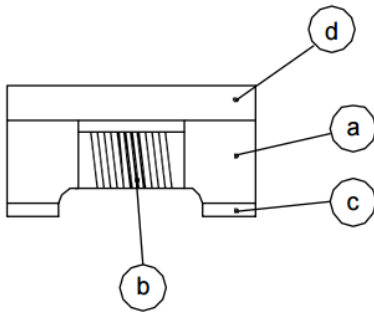
A	B	C	D1	D2	E	G1	G2	H	L
1.2±0.2	1.0±0.2	0.90 Max.	0.35±0.1	0.35±0.1	0.03 Min.	0.65 Ref.	0.30 Ref.	1.10 Ref.	1.55 Ref.

3. Schematic



NOTE: Specifications subject to change without notice. Please check our website for latest information.

4. Material List



- a) Core
- b) Wire
- c) Terminal
- d) Upper Plate

5. General Specification:

- a) Operating Temp. : -40°C ~ +125°C
- b) Storage Temp. : -40°C ~ +125°C
- c) Storage Condition (component in its packaging)
 - i) Temperature: Less than 40°C
 - ii) Humidity : 60%

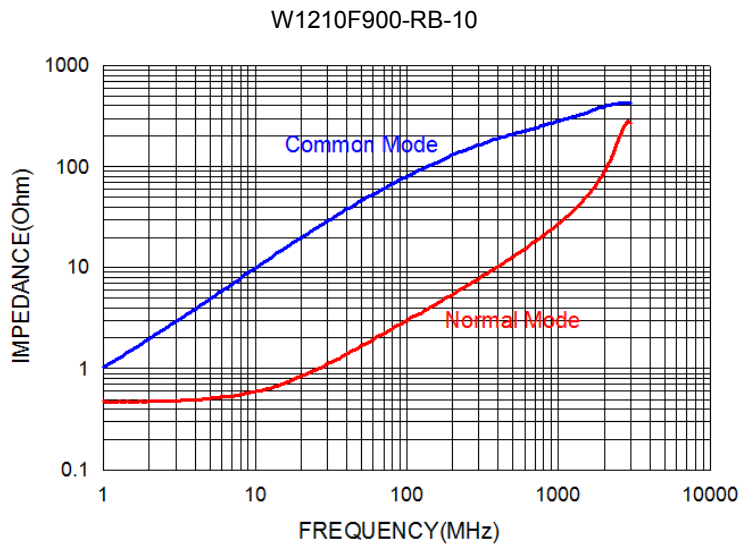
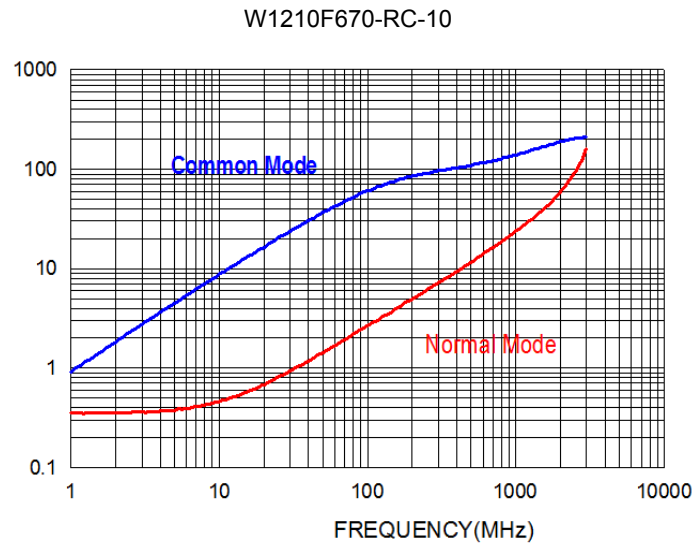
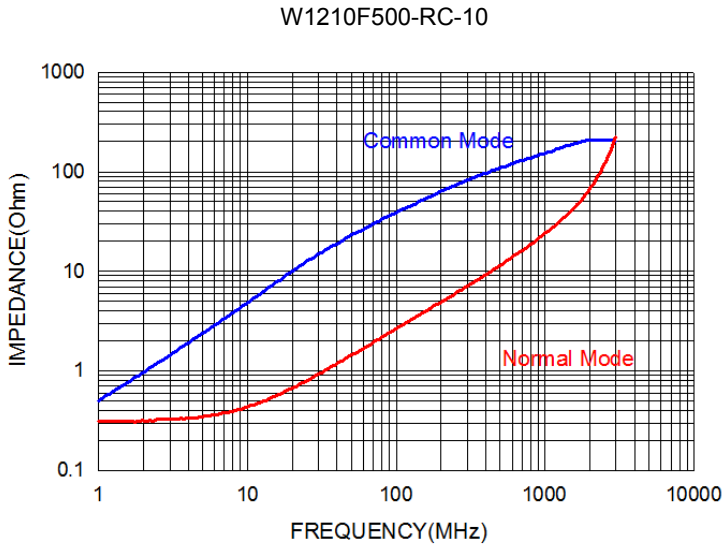
6. Electrical Characteristics

Part No	Impedance (Ω)	Test Frequency (MHz)	DCR (Ω) Max.	Rated Current(mA)	Rated Voltage (Vdc)	Withstand Voltage (Vdc)	IR (Ω) Min.
W1210F500-RC-10	50 ± 25%	100	0.30	250	50	125	10M
W1210F670-RC-10	67 ± 25%	100	0.30	250	50	125	10M
W1210F900-RB-10	90 ± 25%	100	0.40	200	50	125	10M

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7. Characteristic Curves:

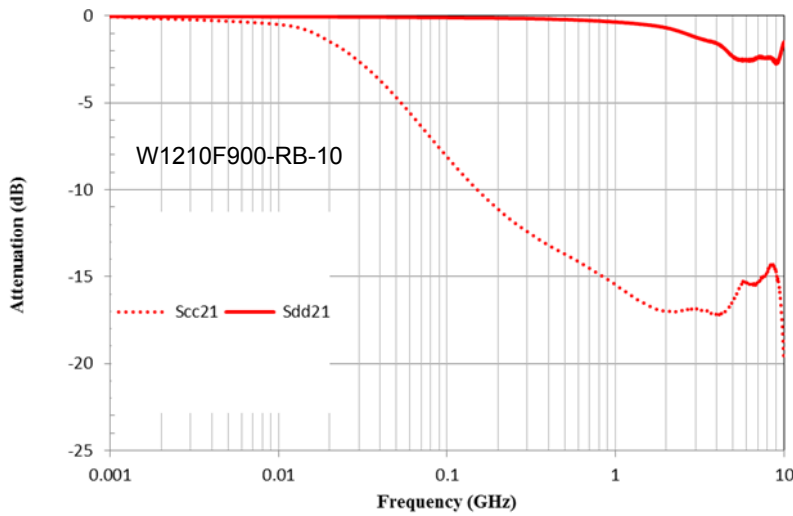
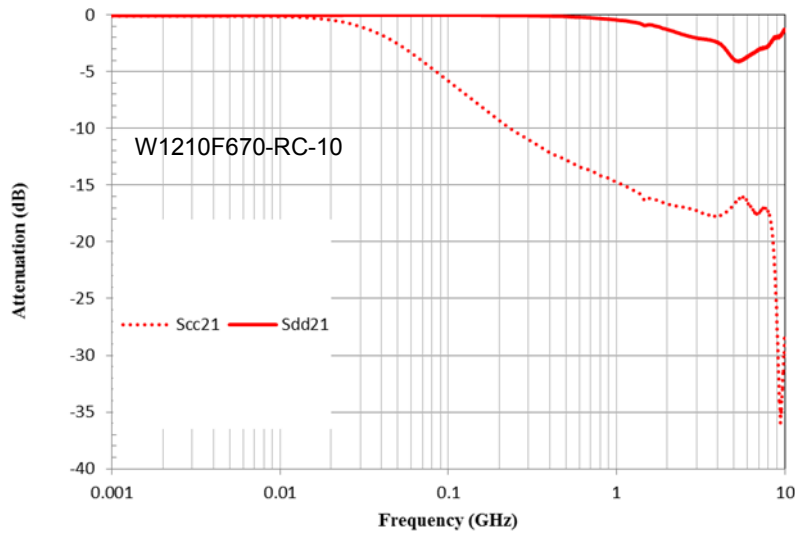
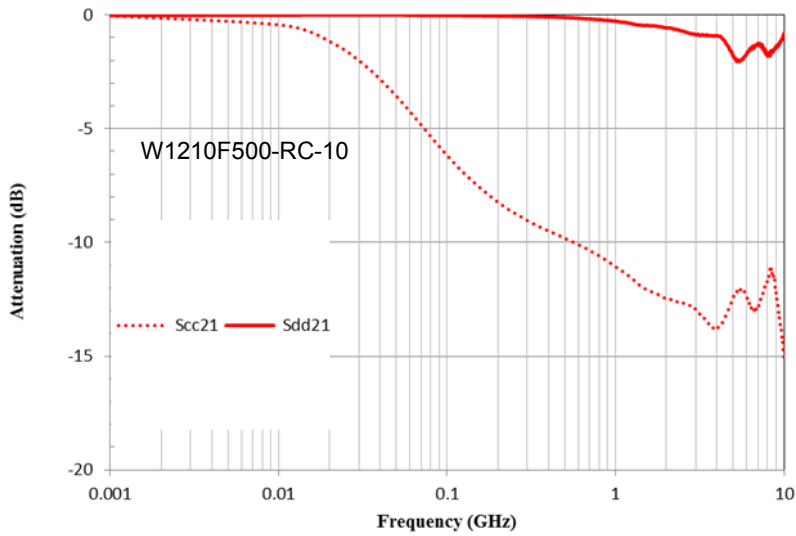
7-1: Impedance versus Frequency



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7-2 Insertion Loss Test



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8. Soldering

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

8-1 Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

8-2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note :

- Preheat circuit and products to 150°C.
- 355°C tip temperature (Max.)
- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (Max.)
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 4~5 sec.

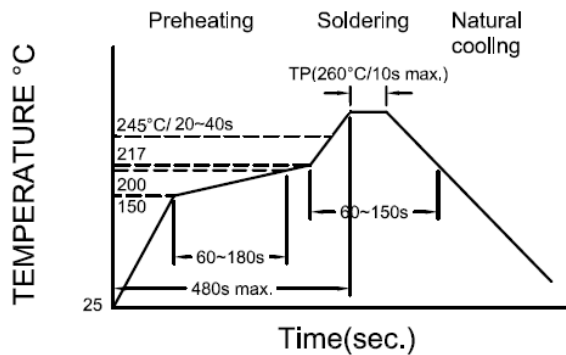


Figure 1. : Re-flow Soldering time
3 times max

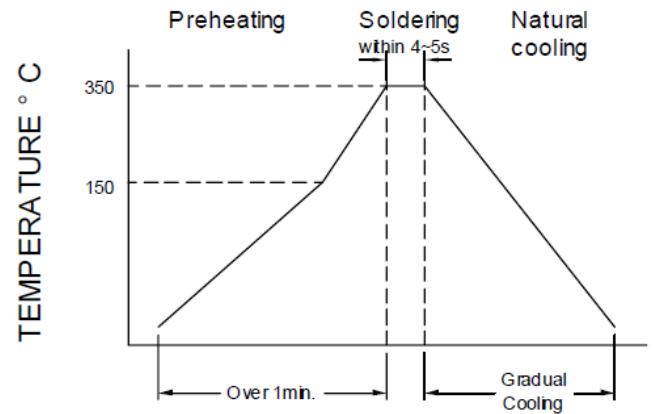
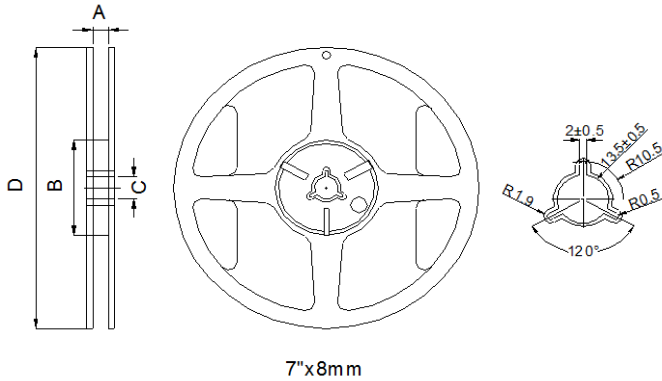


Figure 2. : Iron Soldering time
1 times max

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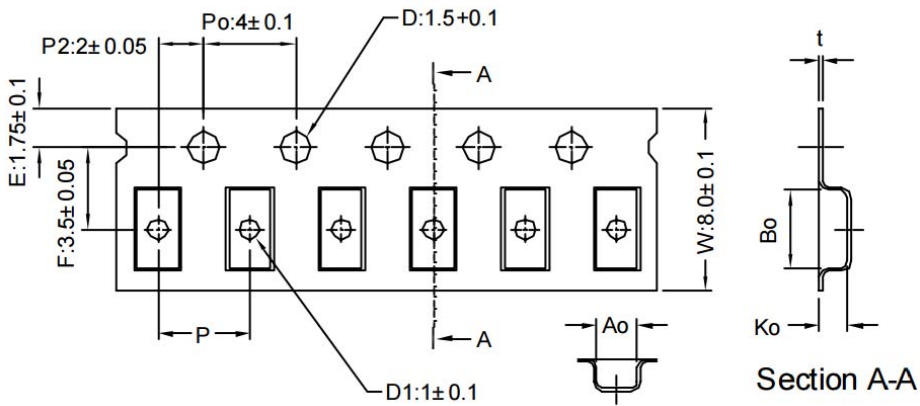
9. Packaging Information

9-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"×8mm	9.0±0.5	60±2	13.5±0.5	178±2

9-2 Tape Dimension



Series	Ao(mm)	Bo(mm)	Ko(mm)	P(mm)	t(mm)
W1210	1.25±0.10	1.50±0.10	1.05±0.10	4.00±0.10	0.22±0.05

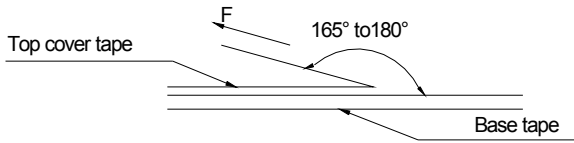
9-3 Packaging Quantity

Series	W1210
Chip/ Reel	3,000
Inner Box	15,000
Middle Box	75,000
Carton	150,000

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9-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

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